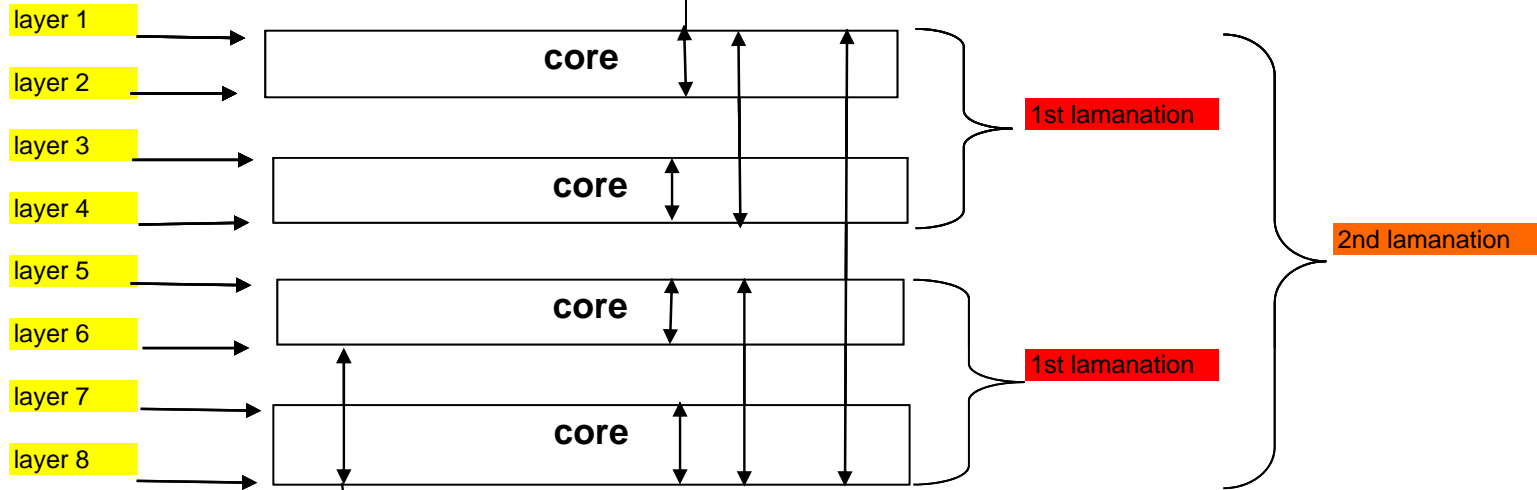


Blind/Buried Vias Design Guidelines



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1. Circuit boards are built in cores so the easiest way to do blind vias is to do sequential lamination. As you can see from the arrow, we would drill one core and then lamination them together and then drill again. Also, keep in mind that you do not want to subject the core to more than 3 lamination cycles because heating and cooling down will eventually breakdown the material.



2. This blind via here from layer 6 to 8 needs to be control depth drilling(usually with a laser). Since layer 5 to 8 has already been laminated the only way to drill this hole is control depth. The hole size has to be 2 to 1 vs depth (10mil hole vs 5mil deep).